

Light is OSRAM

01.02.2021

OS-IN-2021-005

Set Back of Chip in 4 Channel SMT Laser Package

Objective	Set Back of Chip in 4 Channel SMT Laser Package	
Products affected	SPL S4L90A_3 A01	
Background	<ul style="list-style-type: none">▪ Further setback of laser die from lead frame edge will increase process capability index for die attach process.▪ The change will enable scaling to high volume production and ensure automotive grade quality as die placement accuracy along optical axis is considered as critical for some customers.	
Realization	Please refer to 1_cip_OS-IN-2021-005	
Time Schedule	Production Release	CW 46 / 2020
	Start of Delivery	Feb 2021
Assessment	Change of data sheet drawing required No change in electrooptical performance and reliability	

Please direct your inquiry to your local Sales office.

OSRAM Opto Semiconductors
GmbH

Head Office:

Leibnizstrasse 4
93055 Regensburg, Germany
Phone +49 941 850-5
Fax +49 941 850-1002
www.osram-os.com

QUALITY
FIRST

OS-IN-2021-005

Set Back of Chip in 4 Channel SMT Laser Package

Customer Information Package

OS QM CQM ICI | 01.02.2021

Light is OSRAM

OSRAM
Opto Semiconductors

OS-IN-2021-005

Overview

	Page
1. Reason for Change	03
2. Affected Products	04
3. Description of Changes	05
4. Time Schedule	06

OS-IN-2021-005

Set Back of Chip in 4 Channel SMT Laser Package

1. Reason for Change

- Further setback of laser die from lead frame edge will increase process capability index for die attach process.
- The change will enable scaling to high volume production and ensure automotive grade quality as die placement accuracy along optical axis is considered as critical for some customers.

Assessment

- Change of data sheet drawing required
- No change in electrooptical performance and reliability

OS-IN-2021-005

Set Back of Chip in 4 Channel SMT Laser Package

2. Affected Products

Product Name

SPL S4L90A_3 A01

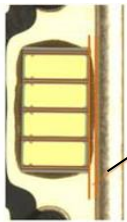
OS-IN-2021-005

Set Back of Chip in 4 Channel SMT Laser Package

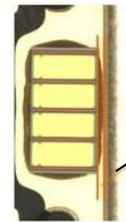
3. Description of Change

Current Situation

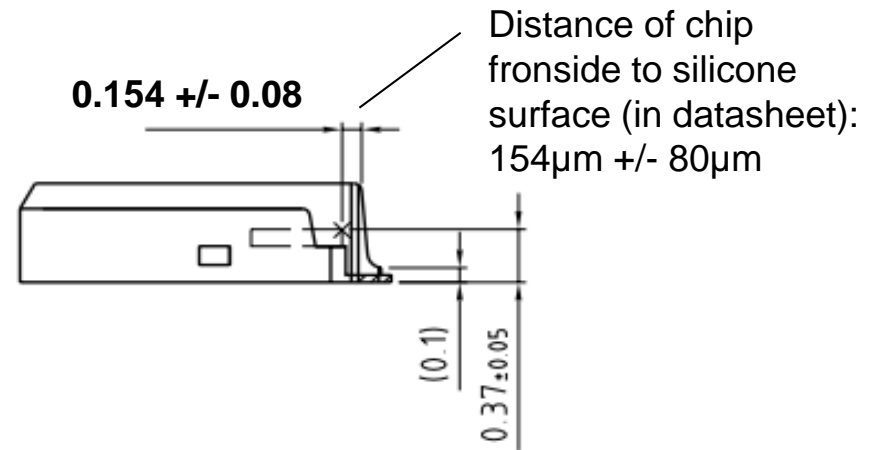
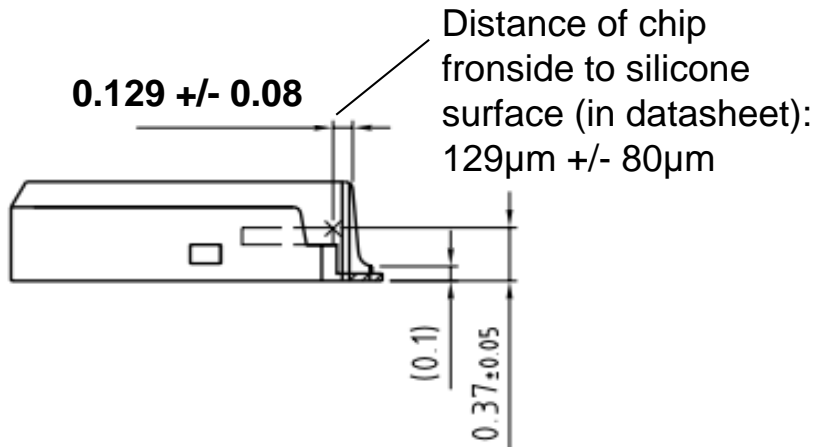
New Situation



Distance of chip from leadframe edge: $25\ \mu\text{m}$ $\pm 25\ \mu\text{m}$



Distance of chip from leadframe edge: $50\ \mu\text{m}$ $\pm 25\ \mu\text{m}$



OS-IN-2021-005

Set Back of Chip in 4 Channel SMT Laser Package

4. Time Schedule

- Production release CW 46 / 2020
- Start of delivery Feb 2021

QUALITY
FIRST

Thank you.